



NOTIFICATION OF TRANSMITTAL OF COPIES OF TRANSLATION OF THE INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Rule 72.2)

From the INTERNATION UREAU

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Applicant's or agent's file reference pt-3197	IMPORTANT NOTIFICATION
International application No. PCT/JP2003/009052	International filing date (day/montle/year) 16 July 2003 (16.07.2003)
Applicant	NEC CORPORATION et al

1. Transmittal of the translation to the applicant.

The International Bureau transmits herewith a copy of the English translation made by the International Bureau of the international preliminary examination report established by the International Preliminary Examining Authority.

2. Transmittal of the copy of the translation to the elected Offices.

The International Bureau notifies the applicant that copies of that translation have been transmitted to the following elected Offices requiring such translation:

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3. Reminder regarding translation into (one of) the official language(s) of the elected Office(s).

The applicant is reminded that, where a translation of the international application must be furnished to an elected Office, that translation must contain a translation of any annexes to the international preliminary examination report.

It is the applicant's responsibility to prepare and furnish such translation directly to each elected Office concerned (Rule 74.1). See Volume II of the PCT Applicant's Guide for further details.

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Translation





PCT

INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Article 36 and Rule 70)

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Applicant's or agent's file reference pf-3197	FOR FURTHER ACTION	ON Preliminary	eation of Transmittal of International Examination Report (Form PCT/IPEA/416)
International application No.	International filing date (4	lay/month/year)	Priority date (day/month/year)
PCT/JP2003/009052	16 July 2003 (16	5.07.2003)	16 July 2002 (16.07.2002)
International Potent Classification (IPC) or of H01L 29/78, 21/336, 21/316	ational classification and I	PC	
Applicant	NEC CORPOR	RATION	
 This international proliminary examination report has been prepared by this International Proliminary Examining Authority and is transmitted to the applicant according to Article 36. This REPORT consists of a total of			
1	·		
I Basis of the repor	t		
II Priority	11 1 1		
III Non-establishmen	at of opinion with regard to	novelty, inventive	step and industrial applicability
IV Lack of unity of i	invention		4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4
V Reasoned statem citations and exp			
VI Certain documen	its cited		
VII Certain defects in	n the international application	ממ	
VIII Certain observations on the international application			
Date of submission of the demand 16 July 2003 (16.07.2003)		Date of completion	on of this report
		3	0 March 2004 (30.03.2004)
Name and mailing address of the IPEA	Tr .	Authorized offic	or .
Pacsimite No.		Telephone No.	

Form PCT/IPEA/409 (cover sheet) (July 1998)

INTERNATIONAL PRELIMINARY EXAMINATION REPORT

International		ion No.
PCT/	JP20	03/009052

L Basis of			
1. With reg	ard to th	e elements of the international application.*	
∏ th	e interna	tional application as originally filed	
Ծ ա	e descrip		, as originally filed
p		1-31	, filed with the demand
P	ages	filed with the letter of	
р	ages _	, filed with the letter of	
	be olaims	E	, as originally filed
F	ages _	1-3, 5-25, 27-68 , as amended (togethe	r with any statement under Article 19
	pages		
·	pages	4, 26 , filed with the letter of	19 December 2003 (19.12.2003)
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, ,			, filed with the demand
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	e sequen	ce listing part of the description:	, as originally filed
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	pages _	, filed with the letter of	
the in These	the lang the lang the lang the lang or 55.3 regard minary e contain filed to furnish furnish The s boen f	to any nucleotide and/or amino acid sequence disclosed in the inter- xamination was carried out on the basis of the sequence listing: ned in the international application in written form. ogether with the international application in computer readable form. ned subsequently to this Authority in written form. ned subsequently to this Authority in computer readable form. international application as filed has been furnished. tatement that the information recorded in computer readable form is identification. mendments have resulted in the cancellation of: the description, pages	which is: Rule 23.1(b)). ary examination (under Rule 55.2 and/ national application, the international not go beyond the disclosure in the
	片	the description, pages the claims, Nos69-71	
1	A	the drawings, sheets/fig	
5.	ר pevou	eport has been established as if (some of) the amendments had not been mad d the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).	
, in	this repo	if sheets which have been furnished to the receiving Office in response to an it ort as "originally filed" and are not annexed to this report since they d	
** Att	y replace	ment sheet containing such amendments must be referred to under item 1 and	annexed to this report.

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	and the content investigation or industrial applicability;
,	Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability;
٧.	Residuted statement and it is
	citations and explanations supporting such statement
	CICAGOIIS AND OFFICE

1.	Statement			
	Novelty (N)	Claims	9,12-17,19-18.31-33,35-37,39,40,45,46,51-54.56- 64, 67	YES
1404	tagarrià (11)	Claims	1-8,10,11,18,29,10,74,38,91-41,47- 50,55,65,66,66	NO
	Inventive step (IS)		g, 22-7H, 59-64	YES
		Claims Claims	1-8, 10-21, 29-58, 65-68	. NO
	Industrial applicability (IA)	Claims	1-68	· YES
		Claims		NO.

Citations and explanations

- Document 1: JP 2001-332547 A (Toshiba Corporation), 30

 November 2001, paragraphs [0011] to [0026];

 [0063] to [0070]; figs. 3, 5 and 9
- Document 2: US 2001/0023120 A (Yoshitaka Tsunashima), 20 September 2001, paragraphs [0134] to [0143]; fig. 8
- Document 3: JP 2002-184773 A (NEC Corporation), 28 June 2002, entire text; fig. 3
- Document 4: JP 62-118559 A (NEC Corporation), 29 May 1987, entire text
- Document 5: JP 58-93331 A (Tokyo Shibaura Electric Co., Ltd.), 3 June 1983, entire text

The inventions set forth in claims 1 to 8, 10, 11, 18, 29, 30, 34, 38, 41-44, 47-50, 55, 65, 66 and 68 are disclosed in document 1, and therefore lack novelty and do not involve an inventive step.

The inventions set forth in claims 19 to 21 and 56 to 58 do not involve an inventive step in the light of documents 1 and 2. Document 2 sets forth a method of forming a gate insulating film comprising a metal silicate film, wherein a metal film is formed on top of a silicon oxide film, and after heating, the unreacted metal area is

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removed. It would be easy for a person skilled in the art to conceive of applying the technique set forth in document 2 to the invention set forth in document 1, in order to obtain a gate structure with the desired characteristics.

The inventions set forth in claims 12, 31, 45 and 67 do not involve an inventive step in the light of documents 1 and 3. Document 3 sets forth a method of forming an insulating film with a high dielectric constant, wherein a silicon oxide film is formed on a substrate, metal is formed on top of said silicon oxide film, which is then heated to form an insulating film. In this method, the partial pressure of residual oxygen is controlled in order to control the thickness of the silicon oxide film formed on the substrate interface. In the invention set forth in document 1, metal is formed on a silicon oxide film then heated to form an insulating film with a high dielectric constant, therefore the invention set forth in document 1 is understood to also address the problem of controlling the thickness of a silicon oxide film formed at a substrate interface.

It would therefore be easy for a person skilled in the art to employ the technique set forth in document 3 in the invention set forth in document 1, taking said problem into account. Moreover, the values could be optimized by trial and error by a person skilled in the art, therefore specifically limiting these values lacks critical significance.

The inventions set forth in claims 13 and 46 do not involve an inventive step in the light of document 1. It is a known technique in common practice to heat a substrate when forming a film on said substrate, therefore it would be easy for a person skilled in the art to employ

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the aforementioned commonly practiced technique in the invention set forth in document 1 in order to control the reaction between the silicon oxide film and the metal film, to form an insulating film with the desired characteristics.

The inventions set forth in claims 14 to 17 and 51 to 54 do not involve an inventive step in the light of document 1. In the invention set forth in document 1, the thickness of a silicon oxide film formed on top of a substrate and the thickness of a metal film formed on top of said silicon oxide film are design features, and could be optimized through trial and error by a person skilled in the art in order to form an insulating film with the desired characteristics, therefore specifically delimiting these thicknesses is not critically significant.

The invention set forth in claims 32 and 33 does not involve an inventive step in the light of documents 1 and 4. Document 4 sets forth a technique of forming a silicon nitride film between a metal oxide film and a polycrystalline silicon electrode in order to prevent reactions at the interface between a polycrystalline silicon electrode and a metal oxide layer. It would therefore be easy for a person skilled in the art to employ the technique set forth in document 4 in the invention set forth in document 1, in order to prevent a reaction between the gate electrode and the gate insulating film.

The invention set forth in claims 39 and 40 does not involve an inventive step in the light of documents 1 and 5. Document 5 sets forth a technique of forming a metal silicate film by reacting a silicon oxide film with metal in a reducing atmosphere. It would be easy for a person

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skilled in the art to employ the technique set forth in document 5 in the invention set forth in document 1 in order to obtain a metal silicate film with the desired characteristics.

The invention set forth in claims 35 to 37 does not involve an inventive step in the light of document 1. In the invention set forth in document 1, the thickness of the silicate layer and the thickness of the layer which does not include metal elements are design features, and could be optimized by trial and error by a person skilled in the art in order to form an insulating film having the desired characteristics, therefore it would be easy for a person skilled in the art to stipulate the relationship of the size of these film thicknesses. Moreover, specifically delimiting these film thicknesses lacks critical significance.

With regard to the inventions set forth in claims 9, 22 to 28 and 59 to 64, none of the documents cited in the international search report sets forth a gate insulating film structure, wherein a composition of a metal element in the thickness direction of the film has a composition modulation which is low in the lowermost part and uppermost part in the proximity of the silicon area, and high in the central part, and said feature would not be obvious to a person skilled in the art.

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